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Experimental Study on the Effect of the Gate Oxide Thickness and the Epitaxial Layer Resistivity on the Reliability of Low Blocking Voltage Power VDMOSFET during Heavy Ion Exposure

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INTRODUCTION

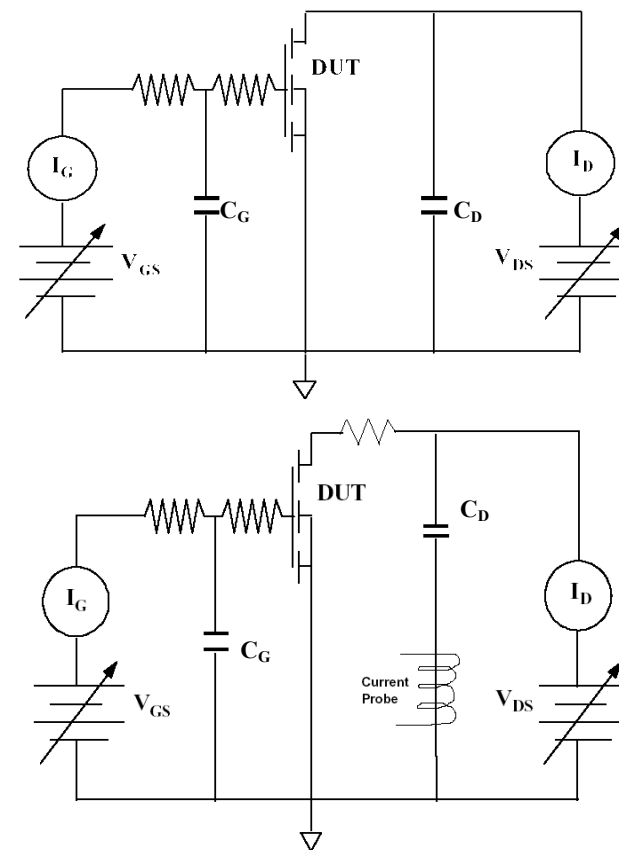
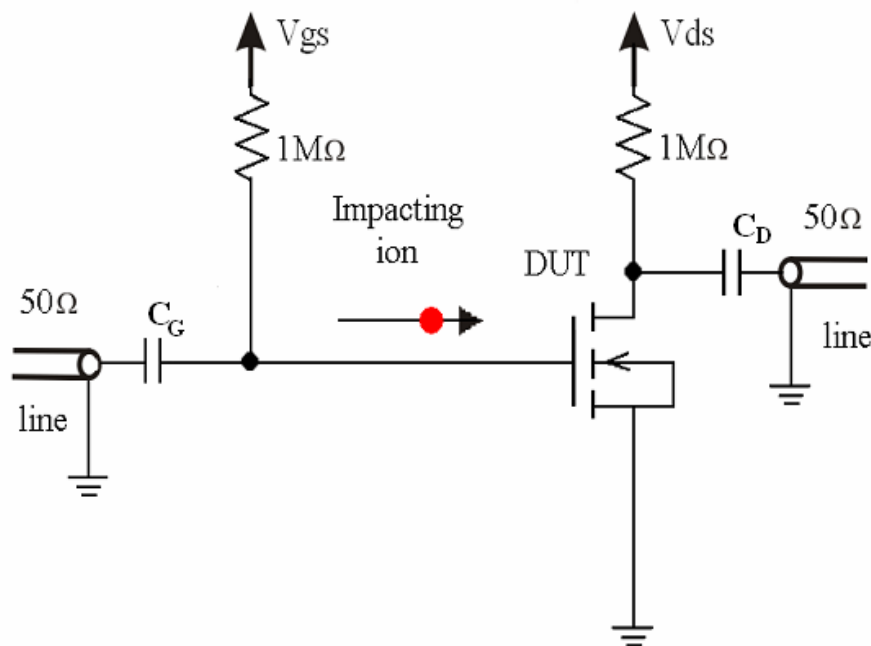
- Power MOSFET's are very important devices for space applications.
- The impact with energetic particles can cause their premature failure. The impact is accompanied by a charge generation that can be experimentally detected.
- The failure mechanisms reported in literature are not completely able to explain the experimental data.
- Further study concerning the correlation between the charge amplification, the oxide/epitaxial layer characteristics and failure mechanism is still necessary.

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EXPERIMENTAL SET-UP



MIL – STD – 750

METHOD 1080

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TESTED DEVICES

DUT	Epitaxial Resistivity	Gate Oxide Thickness
A	Same	T_{oxA}
B	Same	$T_{oxB} = T_{oxA} * 0.9$
C	Same	$T_{oxC} = T_{oxA} * 0.68$

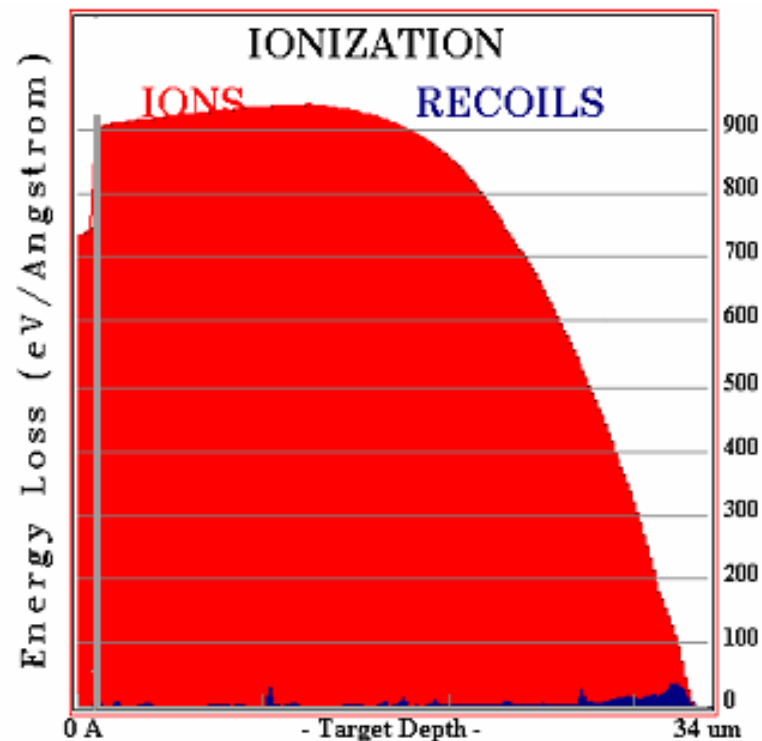
DUT	Gate Lay-Out	Epitaxial Resistivity
D	Same	Low
E	Same	High



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CHOISE OF THE IMPACT ION

REGION	LOW VOLTAGE POWER MOSFET
Metal	3 μm
Silicon Nitride	1 μm
Polysilicon	0.5 μm
Gate Oxide	0.05 μm
Field Oxide	1 μm
Base p	1-2 μm
Epitaxial n	10-15 μm



$^{79}\text{Br}_{35}$, 250 MeV

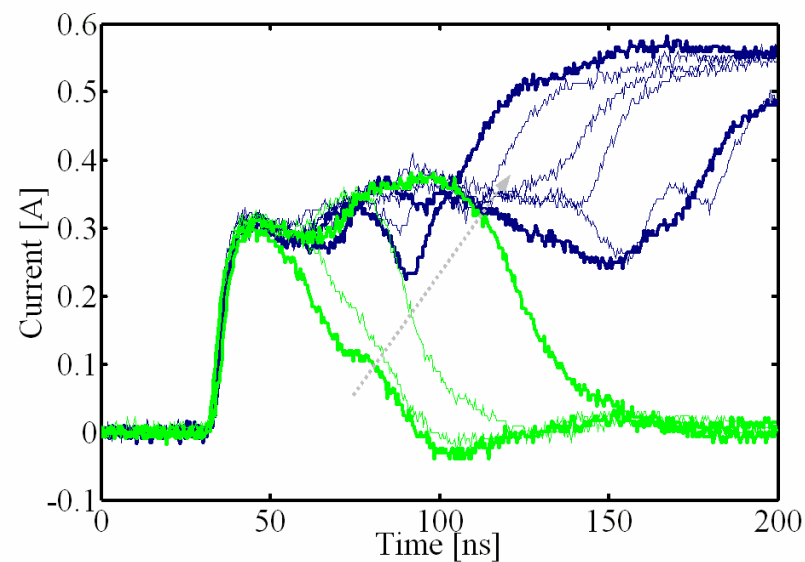
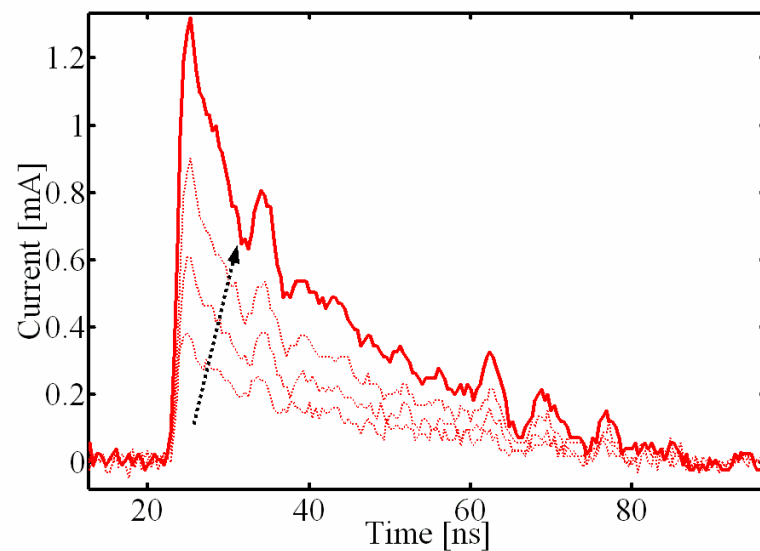
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EXPERIMENTAL RESULTS

Typical Drain Current Waveforms



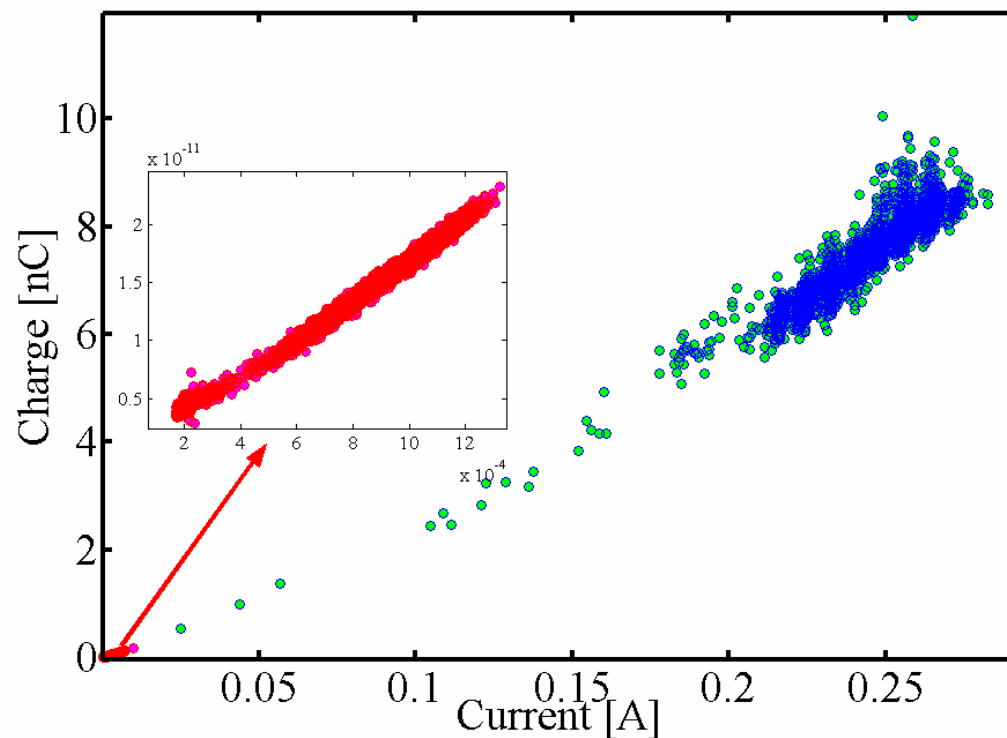
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EXPERIMENTAL RESULTS

Two-dimensional Scatter Plot



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STATISTICAL ANALYSIS

Γ -like Distribution Function

The collected charge at fixed ion species, energy and bias voltages results well described by a Γ -pdf whose formula is:

$$f(x|(a,b)) = \begin{cases} \frac{x^{a-1} e^{-x/b}}{b^a \Gamma(a)}, & x > 0 \\ 0, & x \leq 0 \end{cases}$$

where the parameters a and b have been calculated with the Maximum Likelihood Estimation Technique (MLE)

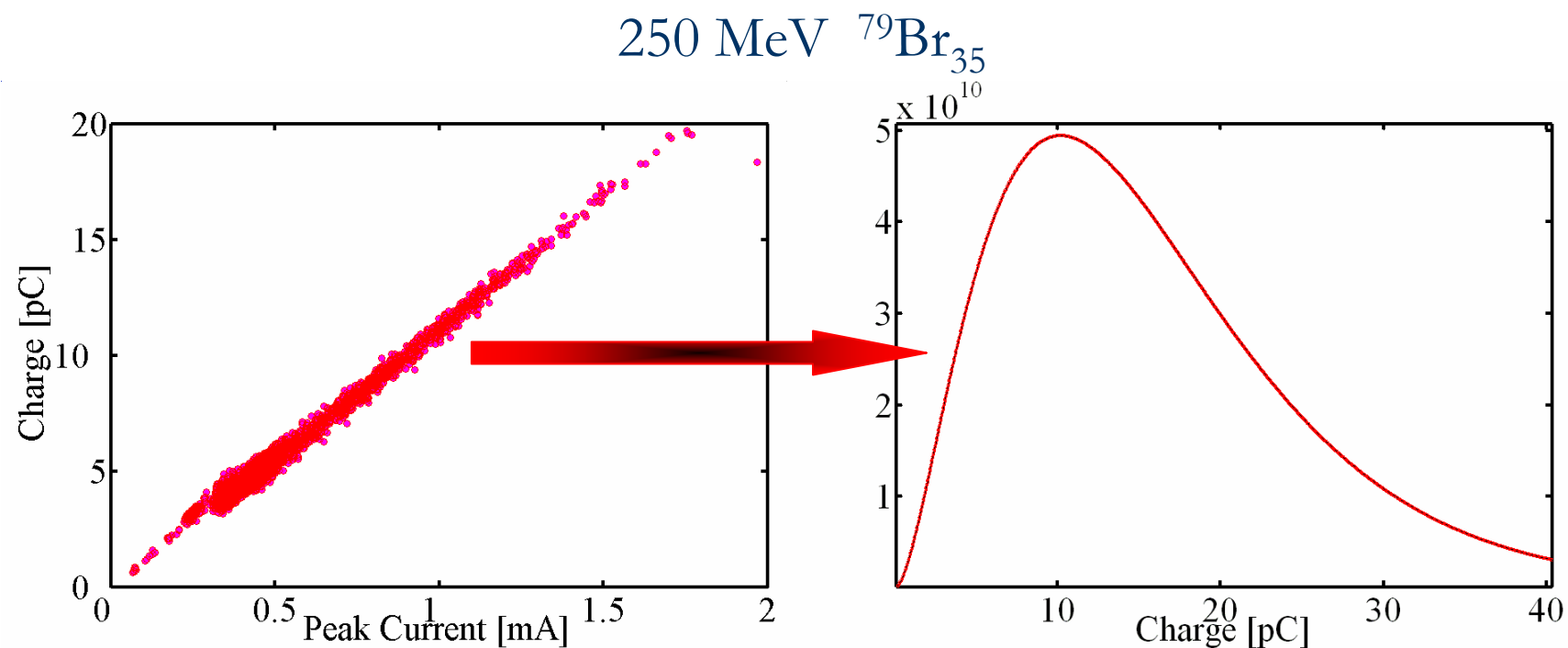
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STATISTICAL ANALYSIS

Γ -like Distribution Function



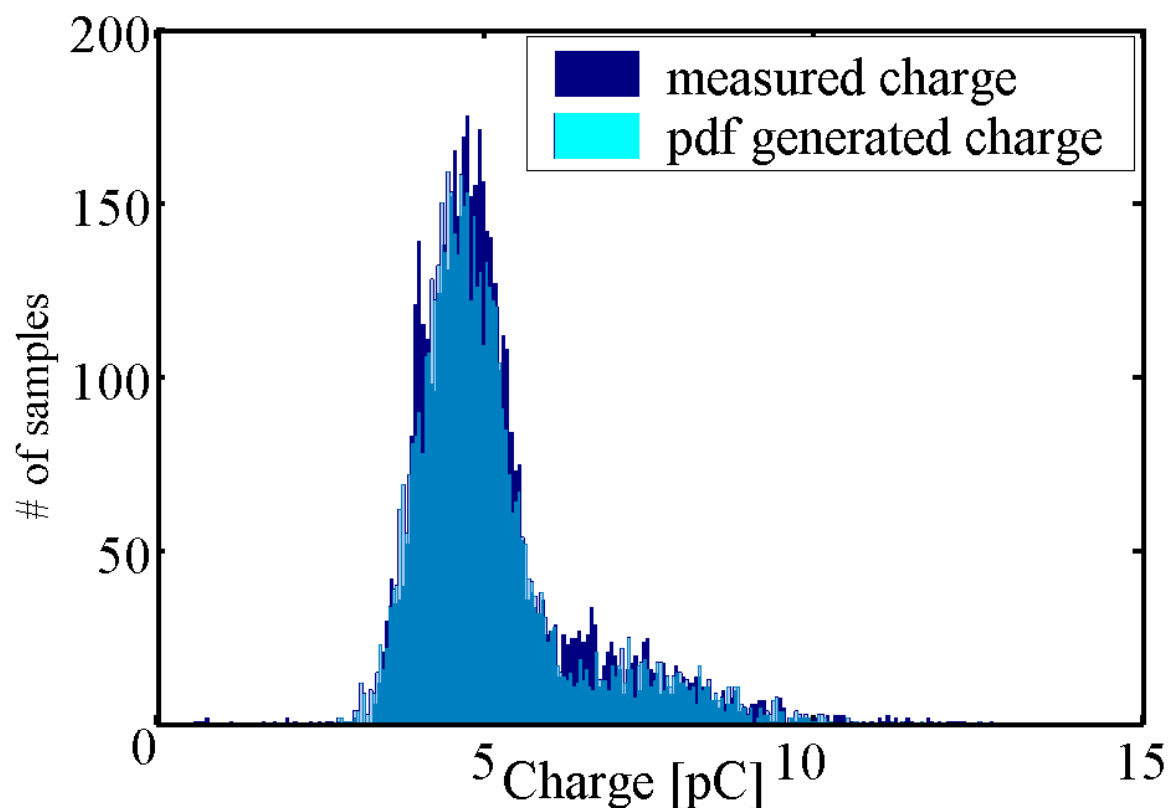
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STATISTICAL ANALYSIS

Γ -like Distribution Function



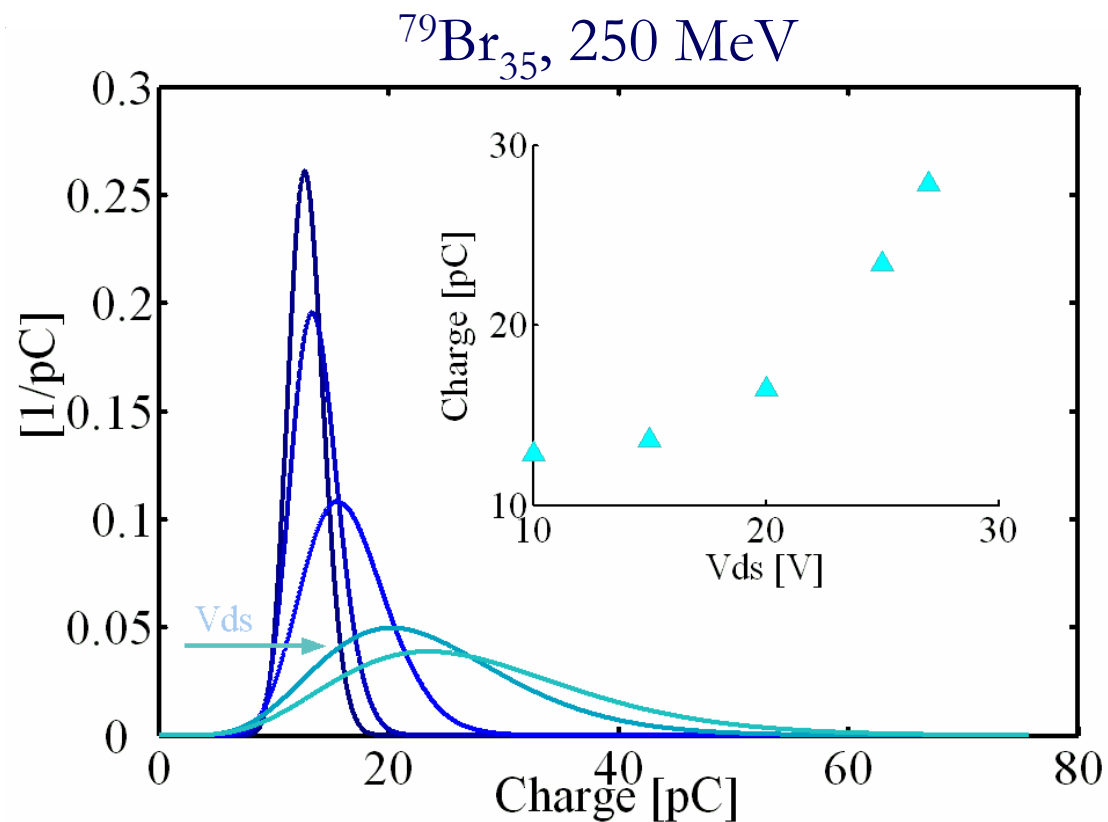
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STATISTICAL ANALYSIS

Γ pdf of the Drain Charge



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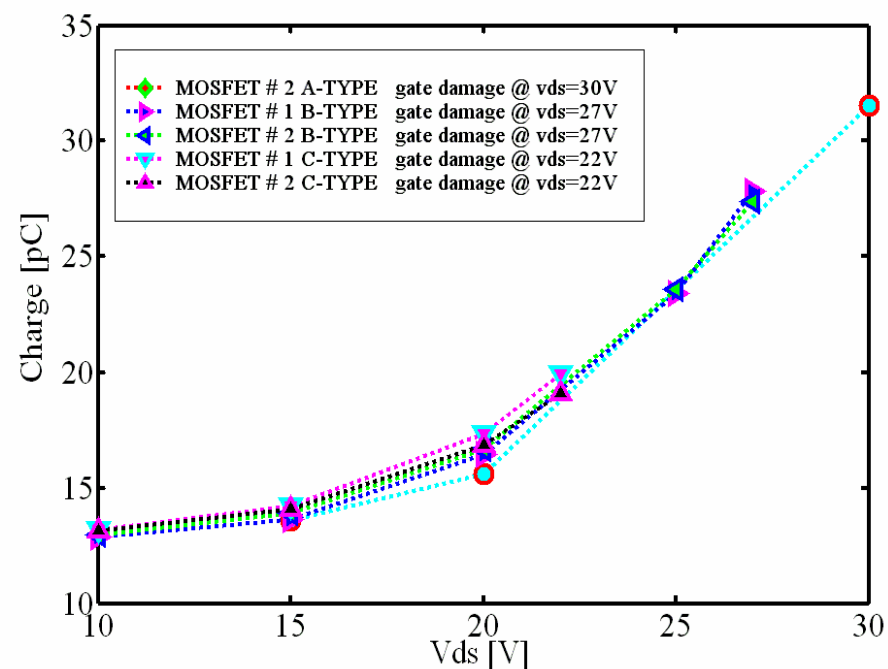


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STATISTICAL ANALYSIS

Mean Drain Generated Charge Versus V_{ds}

DUT	GATE OXIDE THICKNESS	V_{DS}^* @ $V_{GS}=0V$
Mosfet #1 A-TYPE	$T_{OX}A$	30V
Mosfet #2 A-TYPE	$T_{OX}A$	30V
Mosfet #1 B-TYPE	$T_{OX}B = T_{OX}A * 0.9$	27V
Mosfet #2 B-TYPE	$T_{OX}B = T_{OX}A * 0.9$	27V
Mosfet #1 C-TYPE	$T_{OX}C = T_{OX}A * 0.68$	22V
Mosfet #2 C-TYPE	$T_{OX}C = T_{OX}A * 0.68$	22V



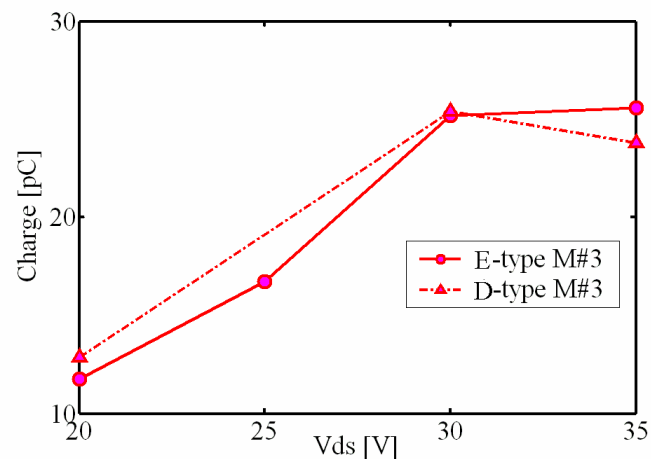
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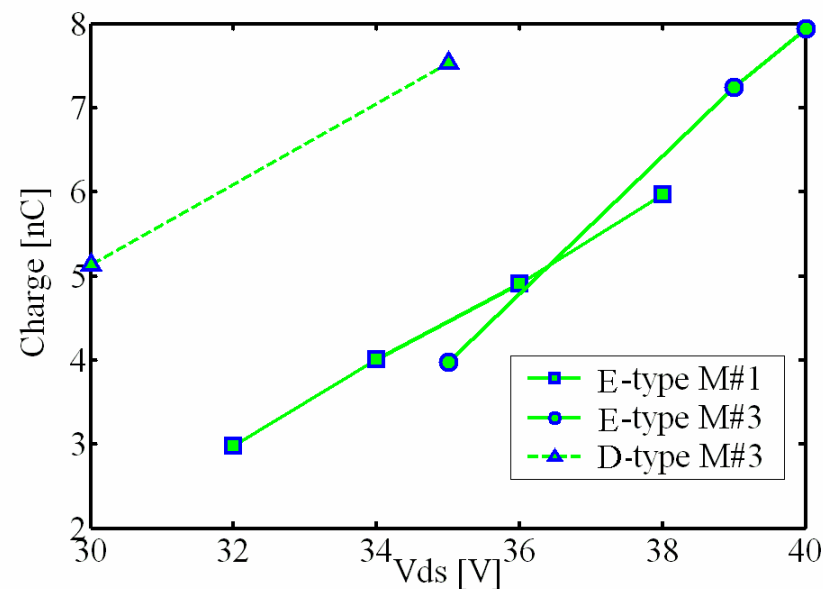
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STATISTICAL ANALYSIS

Mean Drain Generated Charge Versus V_{ds}



DUT	Gate Lay-Out	Epitaxial Resistivity
D	Same	Low
E	Same	High



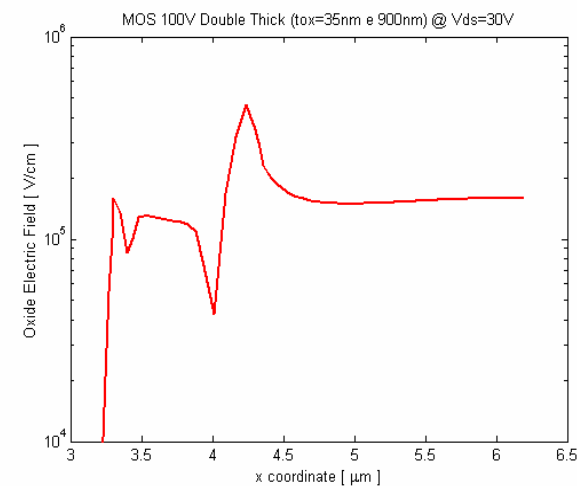
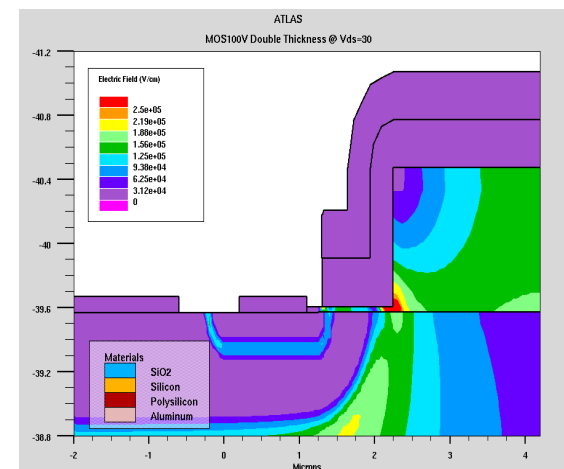
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GATE DAMAGE

DUT	GATE OXIDE THICKNESS	$V_{DS}^* @ V_{GS}=0V$
Mosfet #1 A-TYPE	$T_{OX}A$	30V
Mosfet #2 A-TYPE	$T_{OX}A$	30V
Mosfet #1 B-TYPE	$T_{OX}B = T_{OX}A * 0.9$	27V
Mosfet #2 B-TYPE	$T_{OX}B = T_{OX}A * 0.9$	27V
Mosfet #1 C-TYPE	$T_{OX}C = T_{OX}A * 0.68$	22V
Mosfet #2 C-TYPE	$T_{OX}C = T_{OX}A * 0.68$	22V



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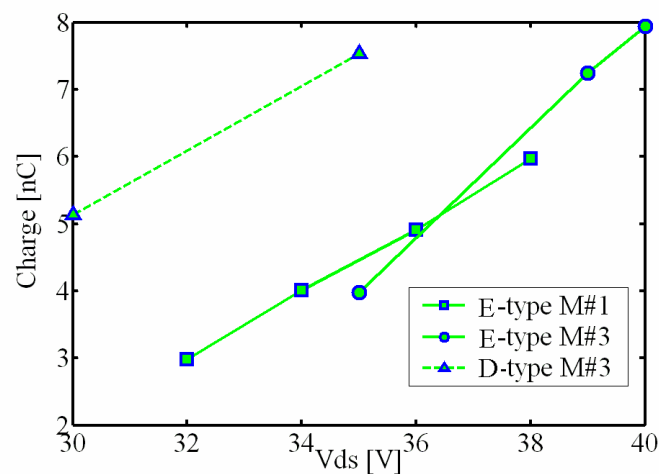
CHARGE GENERATION INSIGHTS

DUT	Gate Lay-Out	Epitaxial Resistivity
D	Same	Low
E	Same	High

$$J_0 = \frac{q\mu_{\text{epi}} N_{\text{epi}} (V_{\text{CB}} + \psi)}{W_{\text{epi}}}$$

$$\frac{J_D}{J_E} = \frac{W_{\text{epi},E} N_D}{W_{\text{epi},D} N_E}$$

$$\frac{J_D}{J_E} = \frac{N_D}{N_E}$$



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CONCLUSIONS

- An experimental investigation on the charge generation and the single event damage of medium voltage power MOSFET as a function of the gate oxide and the epi-layer characteristics has been presented.
- The failure voltage is sensitive to the gate oxide thickness.
- The charge generation is sensitive to the gain of the parasitic BJT.
- In conclusion the experimental data show that the failure mechanisms of the tested devices involves both the gate structure and the drain structure for which an important role is played by the activation of the parasitic bipolar transistor.